# **Dual Channel EMI Filter** with ESD Protection

## **Product Description**

The CM1485 is a 2 channel pi-style EMI filter array with ESD protection, housed in a 6–lead SOT–563 package. The CM1485 has component values of 12 pF – 100  $\Omega$  – 12 pF per channel. The CM1485 has a cut–off frequency of 125 MHz and can be used in applications with data rates up to 48 Mbps. The parts include ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD protection diodes safely dissipate ESD strikes of ±15 kV, well beyond the maximum requirement of the IEC61000–4–2 international standard. Using the MIL–STD–883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30 kV.

This device is particularly well-suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of its small package and easy-to-use pin assignments. In particular, the CM1485 is ideal for EMI filtering and protecting data and control lines for the I/O data ports, LCD display and camera interface in mobile handsets.

The CM1485 is housed in a small, 6–lead SOT–563 package and is available with lead–free finishing.

## Features

- Two Channels of EMI Filtering with Integrated ESD Protection
- Pi-Style EMI Filters in a Capacitor-Resistor-Capacitor (C-R-C) Network
- ±15 kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ±30 kV ESD Protection on Each Channel (HBM)
- Greater than 30 dB Attenuation (Typical) at 1 GHz
- 6-lead SOT-563 Package
- These Devices are Pb-Free and are RoHS Compliant

## Applications

- LCD and Camera Data Lines in Mobile Handsets
- I/O Port Protection for Mobile Handsets, Notebook Computers, PDAs, etc.
- EMI Filtering for Data Ports in Cell Phones, PDAs or Notebook Computers
- Wireless Handsets
- Handheld PCs/PDAs
- LCD and Camera Modules



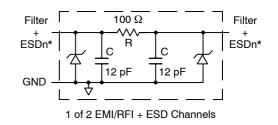
# **ON Semiconductor®**

http://onsemi.com



SOT-563 SE SUFFIX CASE 463A

## **ELECTRICAL SCHEMATIC**



\* See Package/Pinout Diagrams for expanded pin information.

## MARKING DIAGRAM



N85 = CM1485-02SE

M = Month Code

= Pb-Free Package

#### **ORDERING INFORMATION**

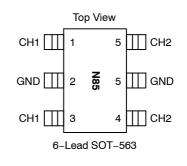
Device	Package	Shipping <sup>†</sup>
CM1485-02SE	SOT-563 (Pb-Free)	5000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **Table 1. PIN DESCRIPTIONS**

6–Lead SOT–563 Package				
Pin	n Name Description			
1	FILTER1	Filter + ESD Channel 1		
2	GND	Ground (Note 1)		
3	FILTER1	Filter + ESD Channel 1		
4	FILTER2	Filter + ESD Channel 2		
5	GND	Ground (Note 1)		
6	FILTER2	Filter + ESD Channel 2		

#### **PACKAGE / PINOUT DIAGRAMS**



1. Pin 2 and Pin 5 must be well grounded at the same time.

## **SPECIFICATIONS**

## Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	-65 to +150	°C
DC Power per Resistor	100	mW
DC Package Power Rating	0.15	W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

## **Table 3. STANDARD OPERATING CONDITIONS**

Parameter	Rating	Units
Operating Temperature Range	-40 to +85	°C

#### Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

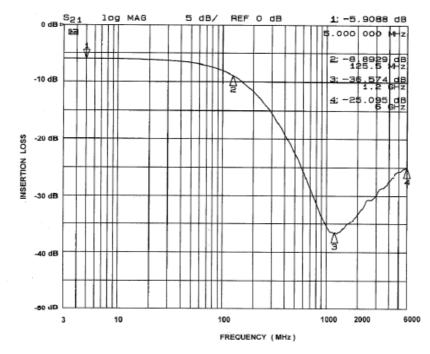
Symbol	Parameter	Conditions	Min	Тур	Max	Units
R	Resistance		90	100	110	Ω
C <sub>TOTAL</sub>	Total Channel Capacitance	At 2.5 V DC Reverse Bias, 1 MHz, 30 mV AC	19.2	24.0	28.8	pF
I <sub>LEAK</sub>	Diode Leakage Current (Reverse Bias)	V <sub>DIODE</sub> = +3.0 V			1.0	μA
V <sub>BR</sub>	Breakdown Voltage Positive Clamp	I <sub>LOAD</sub> = 1 mA	6.0	7.0		V
V <sub>ESD</sub>	In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4	(Note 2)	±30 ±15			kV
R <sub>DYN</sub>	Dynamic Resistance Positive Negative			2.3 0.9		Ω
f <sub>C</sub>	Cut–off Frequency $Z_{SOURCE}$ = 50 $\Omega$ , $Z_{LOAD}$ = 50 $\Omega$			125		MHz
A <sub>1GHz</sub>	Absolute Attenuation @ 1 GHz from 0 dB Level	$Z_{\text{SOURCE}} = 50 \ \Omega$ , $Z_{\text{LOAD}} = 50 \ \Omega$ , DC Bias = 0 V (Notes 1 and 3)		35		dB
A <sub>800MHz</sub> – 6GHz	Absolute Attenuation @ 800 MHz to 1 GHz from 0 dB Level	$Z_{\text{SOURCE}} = 50 \ \Omega$ , $Z_{\text{LOAD}} = 50 \ \Omega$ , DC Bias = 0 V (Notes 1 and 3)		30		dB

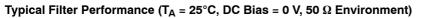
T<sub>A</sub> = 25°C unless otherwise specified.
ESD applied to input and output pins with respect to GND, one at a time.

3. Attenuation / RF curves characterized by a network analyzer using microprobes.

## CM1485

## **PERFORMANCE INFORMATION**







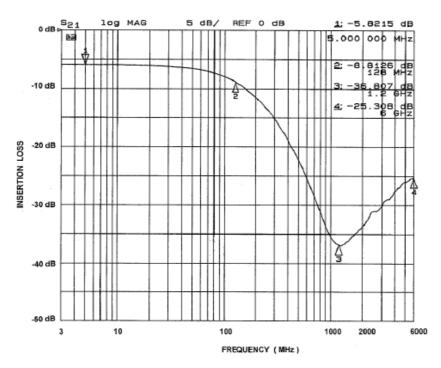
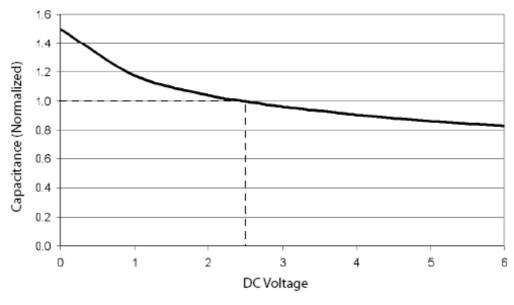
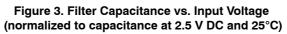


Figure 2. Insertion Loss vs. Frequency (FILTER2 Input to GND)

# CM1485

# PERFORMANCE INFORMATION (Cont'd)





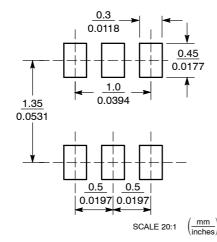
## CM1485

#### PACKAGE DIMENSIONS

SOT-563, 6 LEAD CASE 463A-01 **ISSUE F** 

D -X-5 4 Ē  $H_{F}$ \_V 0 1 2 3 TT b 6 PL С е  $\oplus$ 0.08 (0.003) M X Y

#### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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IS THE MINIMUM THICKNESS OF BASE MATERIAL. MILLIMETERS INCHES MIN NOM MAX MIN NOM MAX DIM Α 0.50 0.55 0.60 0.020 0.021 0.023 b 0 17 0 22 0 27 0 007 0 009 0 011 **C** 0.08 0.12 0.18 0.003 0.005 0.007 **D** 1.50 1.60 1.70 0.059 0.062 0.066 **E** 1.10 1.20 1.30 0.043 0.047 0.051 0.5 BSC 0.02 BSC е

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS

MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS

L 0.10 0.20 0.30 0.004 0.008 0.012 **H**<sub>F</sub> 1.50 1.60 1.70 0.059 0.062 0.066

STYLE 1: PIN 1. EMITTER 1 2. BASE 1
3. COLLECTOR 2
4. EMITTER 2

NOTES

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5 BASE 2 6. COLLECTOR 1